

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 4, at prenumbered line 26, has been amended as follows:

Then, as shown in Fig. 1B, the first substrate 110 is laminated with a sacrificial film 120. The sacrificial film 120 may be a low cost, etchable metal film, such as copper foil. Moreover, a partially cured resin 130 is formed between the first substrate 110 and the sacrificial film 120 to form a laminated substrate. The partially cured resin 130 is cured from 5 to 50%, and more ~~particularly~~ preferably, the partially cured resin 130 is cured 5 to 15%. After laminating the first substrate 110 with the sacrificial film 120, the partially cured resin 130 is pressed via the sacrificial film 120 to have an uniform thickness. Therefore, the formation of unwanted particles during processes and the contamination of the partially cured resin 130 will be greatly reduced. Moreover, the partially cured resin 130 can be easily processing and will not stick to the tooling. The partially cured resin 130 has multi-stage thermosetting property, which can be partially cured (in B-stage) under proper curing temperature and conditions. The partially cured resin 130 can be made of epoxy resin, BT (Bismaleimide Triazine) resi or PI (Polyimide) resin. The partially cured resin 130 can be prepreg containing glass fibers, preferably, the partially cured resin 130 contains metal particles, such as silver particles to enhance heat conductivity of the partially cured resin 130.